



Material Content Data Sheet



Sales Product Name		TLE7368-2E		Issued		27. September 2017			
MA#		MA001114798							
Package		PG-DSO-36-51		Weight*		733.31 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	14.773	2.01	2.01	20146	20146	
leadframe	inorganic material	phosphorus	7723-14-0	0.092	0.01		125		
		non noble metal	zinc	7440-66-6	0.366	0.05		499	
		non noble metal	iron	7439-89-6	7.322	1.00		9985	
wire	non noble metal	non noble metal	copper	7440-50-8	297.304	40.54	41.60	405429	416038
		non noble metal	copper	7440-50-8	1.814	0.25	0.25	2474	2474
		encapsulation	organic material	carbon black	1333-86-4	0.798	0.11		1088
	plastics	epoxy resin	-	36.690	5.00		50034		
		inorganic material	silicondioxide	60676-86-0	361.319	49.28	54.39	492726	543848
leadfinish	non noble metal	tin	7440-31-5	8.119	1.11	1.11	11072	11072	
plating	noble metal	silver	7440-22-4	0.802	0.11	0.11	1093	1093	
glue	plastics	epoxy resin	-	0.977	0.13		1332		
		noble metal	silver	7440-22-4	2.931	0.40	0.53	3997	5329
*deviation	< 10%				Sum in total:	100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com